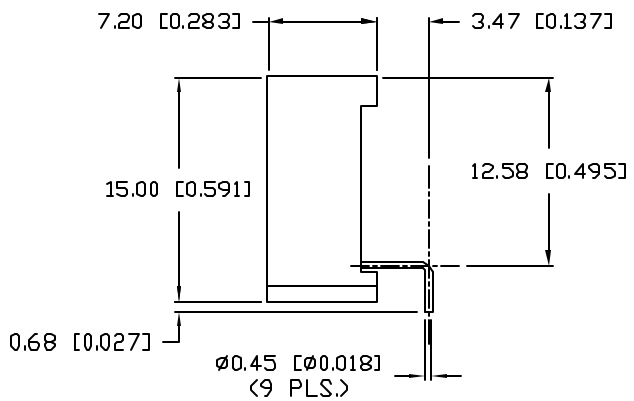
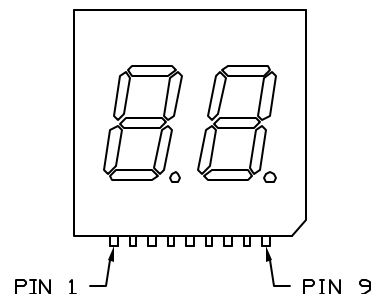


UNCONTROLLED DOCUMENT

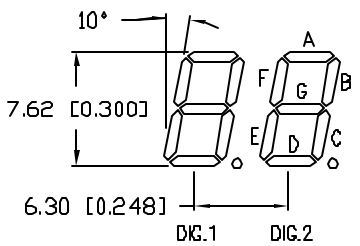
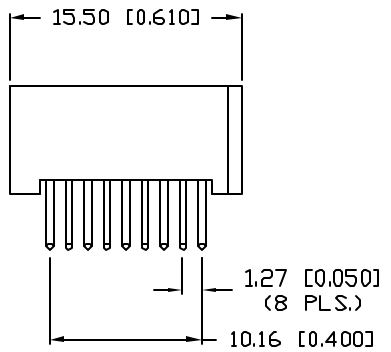
PART NUMBER  
LDD-E302NI-RA

REV.  
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR.	2.16.99
B	E.C.N. #10BRDR. & REDRAWN IN 3D.	6.21.03
C	E.C.N. #11424.	6.26.07



DIGIT DETAIL



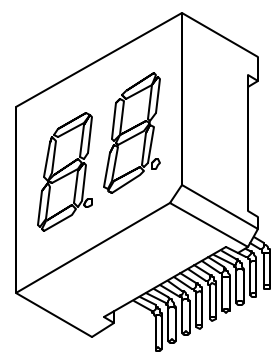
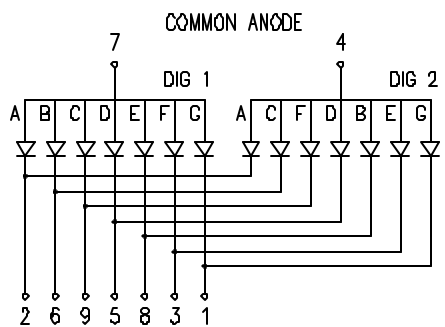
ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		2500		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	GREEN				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIPS

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.6	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$



UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=<sup>+DECIMAL PRECISION</sup>-0.00 <sup>MAX.=+0.00</sup>-DECIMAL PRECISION

REV. C	PART NUMBER LDD-E302NI-RA
-----------	------------------------------

CONFIDENTIAL INFORMATION  
THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.



290 E. HELEN ROAD  
PALATINE, IL 60067-6976  
PHONE: +1.847.359.2790  
US WEB: www.lumex.com  
TW WEB: www.lumex.com.tw

0.30" SEVEN SEGMENT, DUAL DIGIT, LED DISPLAY,  
565nm GREEN CHIPS, GRAY FACE WITH WHITE SEGMENTS,  
MULTIPLEXED, COMMON ANODE, RIGHT ANGLE LEADS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JN	CHECKED BY:	APPROVED BY:	DATE: 2.5.96
			PAGE: 1 OF 1
			SCALE: N/A